What is claimed is:

1. A photodetector packaging system, comprising:

an insulating substrate with a shoulder section; and

a wire bond for coupling the photodetector to the insulating substrate at the shoulder section.

2. The system of Claim 1, further comprising:

optical fiber that directs incident light directly to the photodetector.

3. A method for packaging a photodetector, comprising:

mounting the photodetector on a insulating substrate with a shoulder section; and

coupling the photodetector to the insulating substrate shoulder section with a wire bond.

4. The method of Claim 3, wherein the photodetector is mounted on the insulating substrate such that the photodetector directly receives incident light from an optical fiber.

5. A system for packaging photodetectors, comprising:

an insulating substrate with conducting vias; and

a wire bond that couples the photodetector to the insulating substrate at the conducting vias.

6. The system of Claim 5, further comprising:

conducting tabs coupled to the conducting vias.

7. The system of Claim 6, wherein the metal tabs are coupled to a transimpedance amplifier by a wire bond.

8. The system of Claim 7, wherein the transimpedance amplifier is coupled to a limiting amplifier by a wire bond.

9. The system of Claim 8, wherein the limiting amplifier is coupled to electrical outputs.

10. A method for packaging a photodetector, comprising:

coupling the photodetector to a insulating substrate using conducting vias.

11. The method of Claim 10, wherein the photodetector is coupled to the insulating substrate by a wire bond.

12. The method of Claim 10, further comprising:

coupling the insulating substrate at the conducting vias to metal tabs.

13. The method of Claim 12, further comprising:

coupling the metal tab to a transimpedance amplifier.

14. The method of Claim 13, further comprising:

coupling the transimpedance amplifier to a limiting amplifier.